



*JFW*

**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q73159

Hien Boon TAN , et al.

Appln. No.: 10/721,384

Group Art Unit: 2826

Confirmation No.: 6008

Examiner: Alexander O. Williams

Filed: November 26, 2003

For: **HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE AND METHOD OF MANUFACTURING THE PACKAGE**

**EXCESS CLAIM FEE PAYMENT LETTER**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

An Amendment Under 37 C.F.R. § 1.111 is attached hereto for concurrent filing in the above-identified application. The resulting excess claim fee has been calculated as shown below:

	After Amendment		Highest No. Previously Paid For						
All Claims	<u>25</u>	-	<u>24</u>	=	<u>1</u>	X	<u>\$50.00</u>	=	<u>\$50.00</u>
Independent	<u>2</u>	-	<u>3</u>	=		X	<u>\$200.00</u>	=	<u>\$0.00</u>
					<b>TOTAL</b>			=	<b><u>\$50.00</u></b>

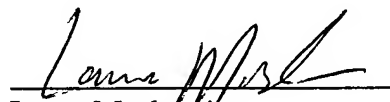
**EXCESS CLAIM FEE PAYMENT LETTER**

U.S. Application No. 10/721,384

**Q73159**

A check for the statutory fee of \$50.00 is attached. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this letter is enclosed.

Respectfully submitted,

  
Laura Moskowitz  
Registration No. 55,470

SUGHRUE MION, PLLC  
Telephone: (202) 293-7060  
Facsimile: (202) 293-7860

WASHINGTON OFFICE

**23373**

CUSTOMER NUMBER

Date: January 28, 2005